

## Product Change Notice (PCN)

**Subject:** Datasheet specification change for Listed Intersil ISL32704E\* Products

**Publication Date:** 2/13/2018

**Effective Date:** 2/13/2018

**Revision Description:**

Initial Release

**Description of Change:**

This notice is to inform you that Intersil has updated ISL32704E\* datasheet. The updates include changes to the following : -

#	Change details	From	To	Unit
1	Thermal Resistance – Junction to Ambient ( $\theta_{JA}$ )			
	16Ld WB-SOIC Package	60	34	°C/W
	16Ld QSOP Package	60	63	°C/W
2	Thermal Resistance – Junction to Case ( $\theta_{JC}$ )			
	16Ld WB-SOIC Package	12	17	°C/W
	16Ld QSOP Package	10	35	°C/W

**Affected Product List**

ISL32704EIAZ	ISL32704EIBZ
ISL32704EIAZ-T	ISL32704EIBZ-T
ISL32704EIAZ-T7A	ISL32704EIBZ-T7A

**Reason for Change:**

The correction to the datasheet aligns the documentation with the product characteristics. Details regarding the change are contained on the following page. The product datasheet is available on the Renesas web site at : -

<https://www.intersil.com/content/dam/intersil/documents/isl3/isl32704e.pdf>

**Impact on fit, form, function, quality & reliability:**

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

**Product Identification:**

Product affected by this change is identifiable via Renesas's internal traceability system.

**Qualification status:** Complete, see attached

**Sample availability:** 2/13/2018

**Device material declaration:** Available upon request

*Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.*

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: <a href="mailto:PCN-US@Renesas.COM">PCN-US@Renesas.COM</a>	Europe: <a href="mailto:PCN-EU@Renesas.COM">PCN-EU@Renesas.COM</a>	Japan: <a href="mailto:PCN-JP@Renesas.COM">PCN-JP@Renesas.COM</a>	Asia Pac: <a href="mailto:PCN-APAC@Renesas.COM">PCN-APAC@Renesas.COM</a>

Appendix A – Details of Data sheet change (see attached)

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<b>Absolute Maximum Ratings</b> (Note 16)		<b>Thermal Information</b>	
<b>Supply Voltages</b> (Note 6)		<b>Thermal Resistance (Typical)</b>	
VDD1 to GND1	-0.5V to +7V	$\theta_{JA}$ (°C/W)	$\theta_{JC}$ (°C/W)
VDD2 to GND2	7V	16 Ld WB-SOIC Package (Notes 4, 5)	60 12
Input Voltages, D, DE, $\overline{RE}$	-0.5V to (VDD1 +0.5V)	16 Ld QSOP Package (Notes 4, 5)	60 10
<b>Input/Output Voltages</b>		Maximum Junction Temperature (Plastic Package)	-55°C to +150°C
A, B	-8V to +12.5V	Maximum Storage Temperature Range	-55°C to +150°C
R	-0.5V to (VDD1 +1V)	Maximum Power Dissipation (WB-SOIC)	.800mW
Short-Circuit Duration, A, B	Continuous	Maximum Power Dissipation (QSOP)	.675mW
ESD Rating	See "ESD PERFORMANCE" on page 5	Solder Profile	Per JEDEC J-STD-020C, MSL1
		Pb-Free Reflow Profile	see TB493

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<b>Absolute Maximum Ratings</b> (Note 17)		<b>Thermal Information</b>	
<b>Supply Voltages</b> (Note 7)		<b>Thermal Resistance (Typical)</b>	
VDD1 to GND1	-0.5V to +7V	$\theta_{JA}$ (°C/W)	$\theta_{JC}$ (°C/W)
VDD2 to GND2	7V	16 Ld WB-SOIC Package (Notes 5, 6)	34 17
Input Voltages, D, DE, $\overline{RE}$	-0.5V to (VDD1 +0.5V)	16 Ld QSOP Package (Notes 5, 6)	63 35
<b>Input/Output Voltages</b>		Maximum Junction Temperature (Plastic Package)	-55°C to +150°C
A, B	-8V to +12.5V	Maximum Storage Temperature Range	-55°C to +150°C
R	-0.5V to (VDD1 +1V)	Maximum Power Dissipation (WB-SOIC)	.800mW
Short-Circuit Duration, A, B	Continuous	Maximum Power Dissipation (QSOP)	.675mW
ESD Rating	See "ESD PERFORMANCE" on page 5	Solder Profile	Per JEDEC J-STD-020C, MSL1
		Pb-Free Reflow Profile	see TB493